

HPLA 2025: STMicroelectronics

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STMicroelectronics – Catania



STMicroelectronics: Company overview

We are creators and makers of technology



One of the world's largest semiconductor companies



50,000 employees
of which **9,000+** in R&D



\$13.3 billion revenues
in 2024



Over **80** sales & marketing
offices serving over **200,000**
customers across the globe



14 main manufacturing
sites



Signatory of the United Nations Global Compact (UNGC)
Member of the Responsible Business Alliance (RBA)

Where you find us



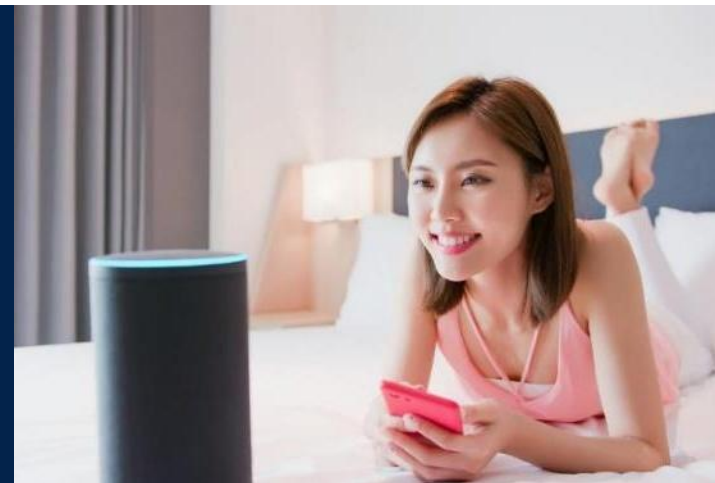
Making **driving** safer, greener, and more connected

Enabling the evolution of **industry** towards smarter, safer, and more efficient factories & workplaces



Making **homes & cities** smarter, for better living, higher security, and to get more from available resources

Making everyday **things** smarter, connected, and more aware of their surroundings



Our products and solutions enable customer innovation

Dedicated automotive ICs



Analog, industrial & power conversion ICs



GP MCU & MPU, Wireless solutions, secure MCU, EEPROM



Discrete & power transistors



MEMS & optical sensing solutions



ASICs based on ST proprietary technologies



Differentiated technologies are our foundation



MEMS
for sensors & micro-actuators

Smart Power: BCD
(Bipolar - CMOS - Power DMOS)

FD-SOI CMOS
FinFET through Foundry

Discrete, Power MOSFET, IGBT
Silicon Carbide, Gallium Nitride

Analog, RF CMOS & BiCMOS,
Silicon photonics

Vertical Intelligent Power

eNVM CMOS

Optical sensing solutions

Packaging technologies

Leadframe – Laminate – Sensor module – wafer level

We are drivers of your innovation

Advanced R&D centers around the world for close collaboration with operations, customers, and partners

~9,300 people working in R&D and product design

~21,000 active and pending patents worldwide

~16% of revenues invested in R&D in 2024

~200 active R&D partnerships

13 fab labs to drive open innovation

~80 startups engaged in our programs

New challenges for engineering in innovation scenarios

Heterogeneous Integration



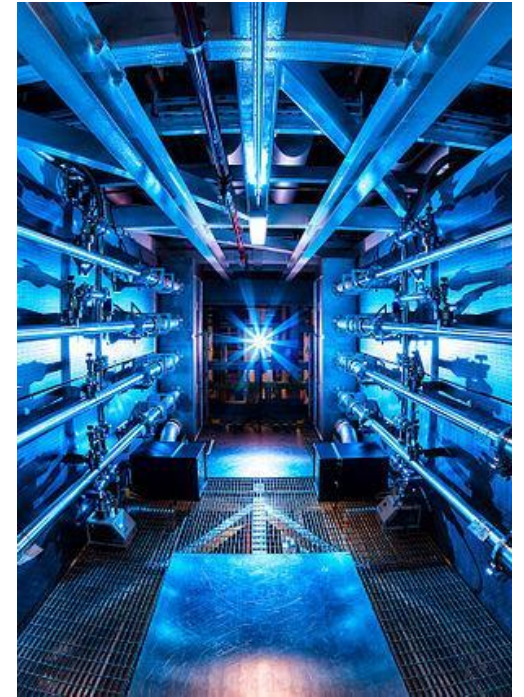
Photonics



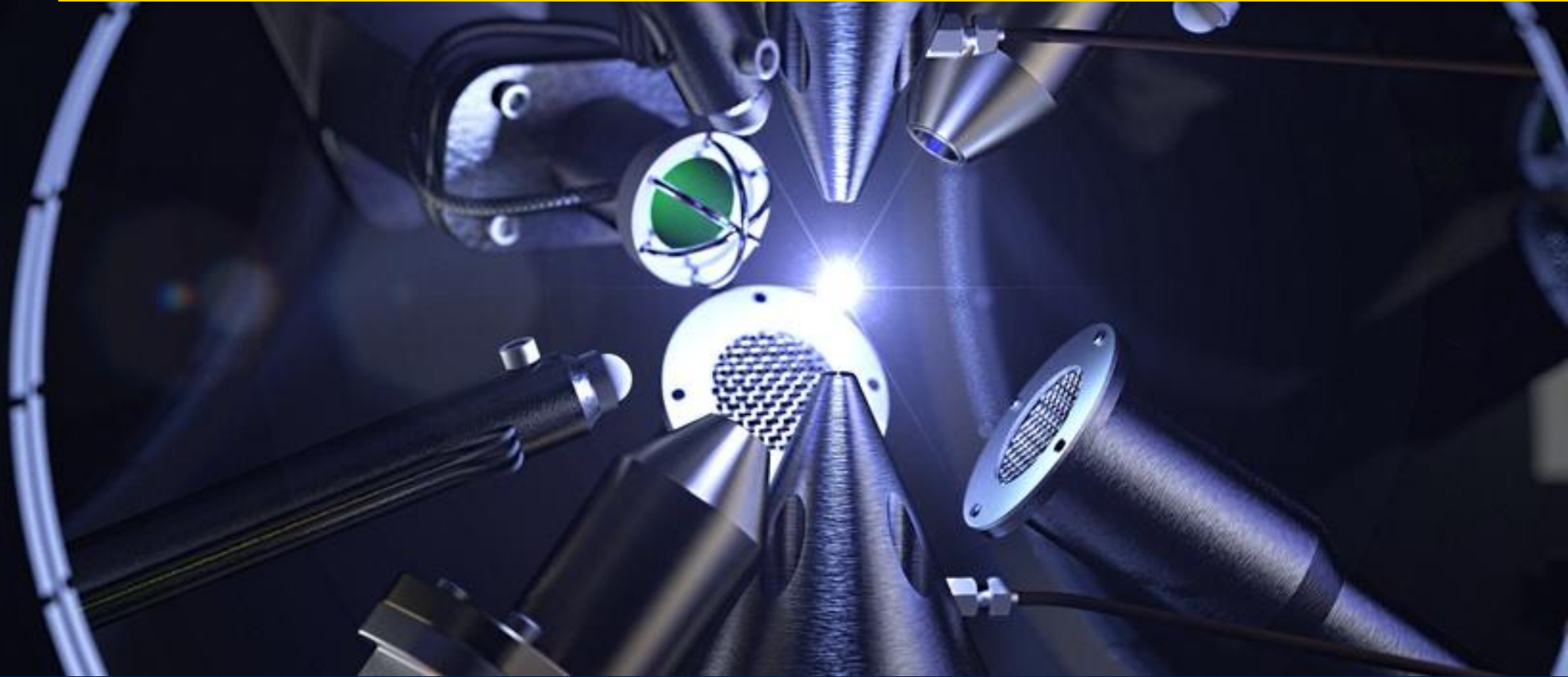
Quantum Technologies



Nuclear Energies



Why are we interested in Nuclear Fusion?



The End-to-End “Energy” Chain

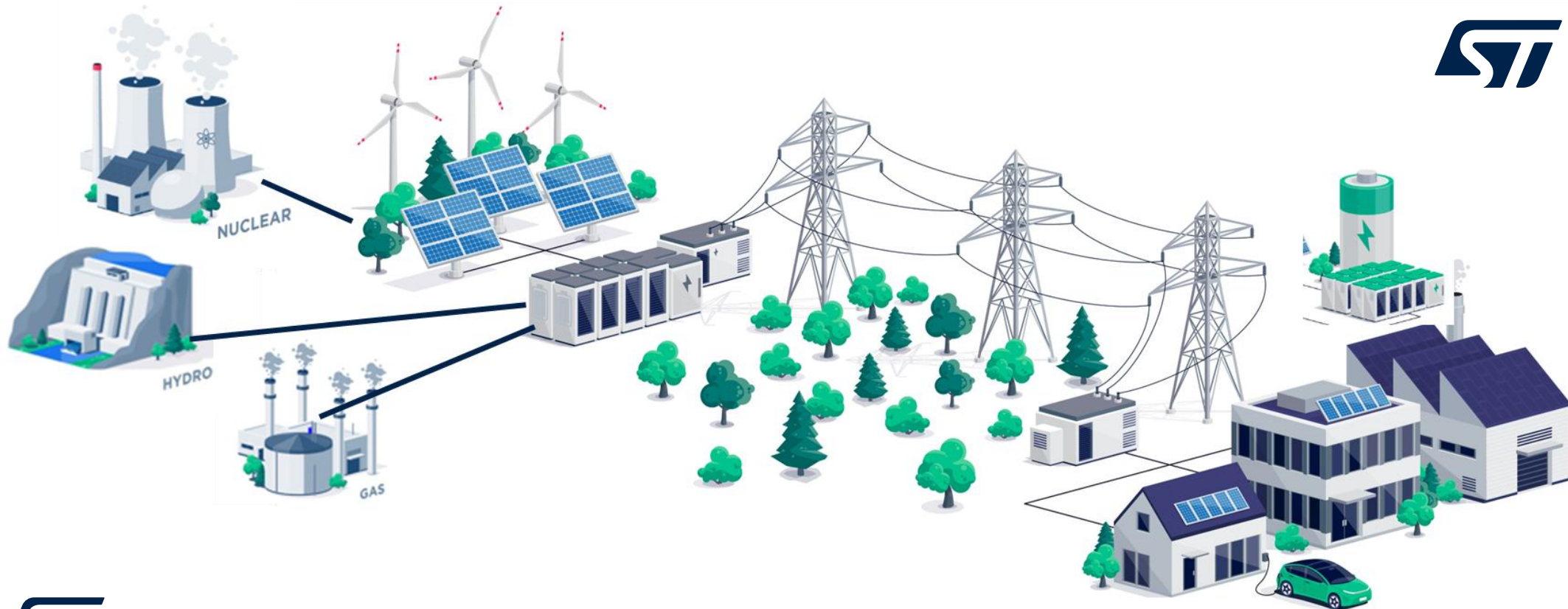
Energy Generation

Medium Voltage (1kV – 30kV) – High Voltage Systems (30kV ~ 150kV)

Energy Transmission

Energy Storage and Utilization

Low Voltage Systems ~1000 Vdc



A new Energy Deal

- By end of 2100, demand for energy is expected to triple due to:
 - population growth & increased urbanization;
 - expanding access to electricity in developing countries;
 - electrification of vehicles (including cars, planes and drones)
- Significant increase (3x) in energy cost, due to geopolitical tensions, requiring world leaders to propose alternative solutions
- Public opinion on nuclear energy improved
 - new mini-reactors with compact design making them very safe.
- Renewable energy sources are not yet fully scalable due to their intermittent nature
- The renewal, modernization, and proliferation of nuclear technologies are underway:
 - fusions, SMR, AMR, Gen3/4 , plant lifetime >60Y, new local usages



An insight into a nuclear power plant

Key functions to perform in Nuclear environments

- **Measure, Actuate, Control & Monitor, Diagnose**
 - **Communicate** (Data and Video)
 - **Identify and localize** (total asset visibility)
 - **Protect, track and guide**
- From ultrahard-to-softer radiation perimeters
 - Nuclear island (extreme radiation, temp., lifetime)
 - Turbine island
 - Industrial Plant (including cooling tower)
 - Front end (low radiation level) & recycling (severe radiation level)
 - **Mixed Nuclear Constraints**
 - Radiation (gamma, neutrons ...): medium <1Mrad to extreme >10Mrad
 - Humidity, Vibration, Temperature
 - RAMS : Reliability - Availability - Maintainability - Safety - Security
 - Lifecycle (obsolescence) & Qualification (authority acceptance)



Main technologies convergence

Power Electronics

- **MOSFETs, IGBTs and Thyristors** power devices for converters and inverters.
- **Silicon Carbide (SiC)** Devices (as WBG Emerging Technology)
- **Motor Drives and Control ICs** for pumps, compressors, robotic actuators
- **Power Converters** for Voltage/current conditioning

Control and Data Acquisition

- **Microcontrollers (MCUs) and Microprocessors (MPU)** for signal processing
- **Analog and Digital ICs** for real-time diagnostics and control systems
- **High-Speed Data Acquisition Systems** to capture and digitize large volumes of sensor data for analysis

Sensors and Detectors

- **Photodiodes and Photodetectors** for light emission, laser signals and scintillation
- **X-ray Detectors** for hi-Res. Spectroscopy,
- **Neutron Detectors** for monitoring fusion reaction
- **CCDs and CMOS Image sensors** for light emission, visible and ultraviolet spectroscopy

MEMS

- **MEMS Sensors** for monitoring temperature, pressure, and magnetic field inside diagnostic ports or reactor components

Discrete & power transistors

Key power technologies & packages for: Car electrification, power management, motor control



High-voltage and low-voltage silicon power MOSFETs (STripFET*, Planar & MDmesh*)
IGBTs. Power bipolar transistors
Silicon carbide MOSFETs
Gallium nitride (GaN) on silicon power and RF transistors
LDMOS & DMOS RF power transistors
ACEPACK* power modules. SLLIMM* intelligent power modules

Diodes, rectifiers, thyristors (SCR), AC switches

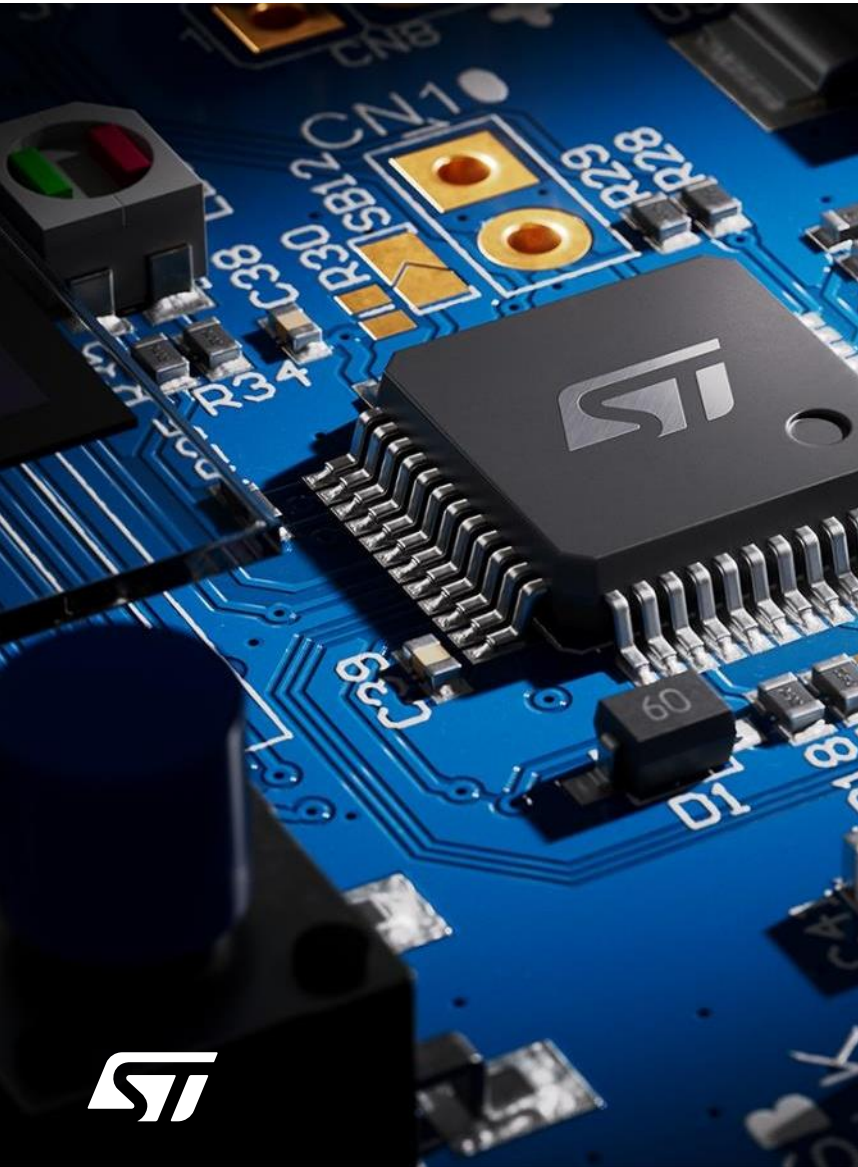
Silicon carbide (SiC) & high-voltage and low-voltage silicon diodes
Ultra-fast & bridge rectifiers
Power Schottky diodes & field-effect rectifiers
Thyristors (SCR) & triacs
ACS* AC switches

Transient voltage suppressors (TVS) EMI filtering & protection ICs

ESD protection
EOS & lightning surge protection
Current limiters
IPAD* integrated EMI and ESD protection devices
Integrated passive devices

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General-purpose MCU & MPU, secure solutions & NFC



General-purpose 32-bit MCU & MPU



STM32* 32-bit general-purpose MCUs and 32/64-bit MPUs

Arm® Cortex® cores

High performance, mainstream, ultralow power MCU offer

Graphics & AI accelerators

Extensive ecosystem with edge AI

Wireless 32-bit MCU



Bluetooth® Low Energy ICs

Zigbee, Thread, Matter

Wi-Fi modules

Sub-1 GHz & Sigfox-compatible devices

LoRaWAN® technology

STM32 DNA, extended ecosystem for RF

Secure solutions



Mobile consumer transactions

Authentication and brand protection

Payment systems

Connected services in cars

NFC & Memory



NFC / RFID Tags

Dynamic NFC tags

NFC / RFID Readers

High-performance & high-endurance EEPROMs

Analog, industrial & power conversion ICs



Power management



- AC/DC & DC/DC
- MOSFET, IGBT, SiC, GaN gate drivers
- Analog / digital controllers
- Linear voltage regulators
- Intelligent power switches
- Galvanic isolation
- Digital power
- Smart power GaN
- Battery management | eFuses

Analog products



- Operational amplifiers, comparators, LDOs
- Current sensing amplifiers
- Filtering & conditioning
- Interfaces & transceivers
- Reset & supervisors
- Powerline communication
- IO-Link
- Rad-hard

Motion control



- Brushed DC motor drivers
- Brushless DC motor drivers
- Stepper motor drivers

Application specific ICs

- PMIC, pre-amps for data storage & servers
- Wireless charging, touch controller, display
- PMIC for personal devices
- Medical ICs

MEMS & optical sensing solutions



Motion sensors



- Accelerometers & gyroscopes
- Inertial modules & smart sensors
- Vibrometers, inclinometers
- Magnetometers
- T-Plus: Motion MEMS with embedded temperature sensor

Environmental & biosensors



- Biosensors (motion + bio-signals)
- Barometers, pressure sensors
- Temperature sensors
- Electrostatic sensors
- MEMS microphones

Micro actuators

- Actuators for printheads
- Piezoelectric actuators
- Electrostatic actuators
- Electromagnetic actuators
- Thermal actuators

Optical sensing solutions



- FlightSense* ToF proximity & multi-zone ranging modules
- 3D FlightSense ToF sensors
- BrightSense* global shutter CMOS sensors
- Ambient light sensors
- Micro-optics
- Custom optical solutions



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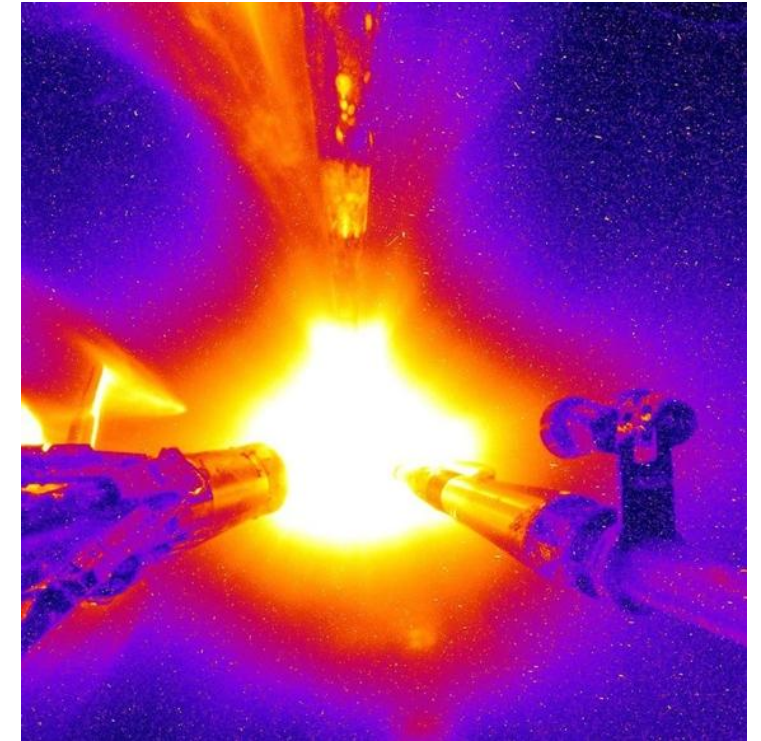
Take aways



Take aways

As nuclear fusion technology advances toward practical energy generation, it presents significant opportunities for semiconductor companies as:

- **Growth in clean energy sector:** strategic positioning in the energy transition.
- **Technological innovation:** developing materials and packaging resistant to extreme conditions.
- **Demand for advanced components:** supplying sensors, microcontrollers and power devices.
- **Research collaborations:** strengthening know-how and visibility in the high-tech sector.



Our technology starts with You



Find out more at www.st.com

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